



### POWER DISSIPATION (DFN(PLP)2020-8)

This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board.

This specification is based on the measurement at the condition below:

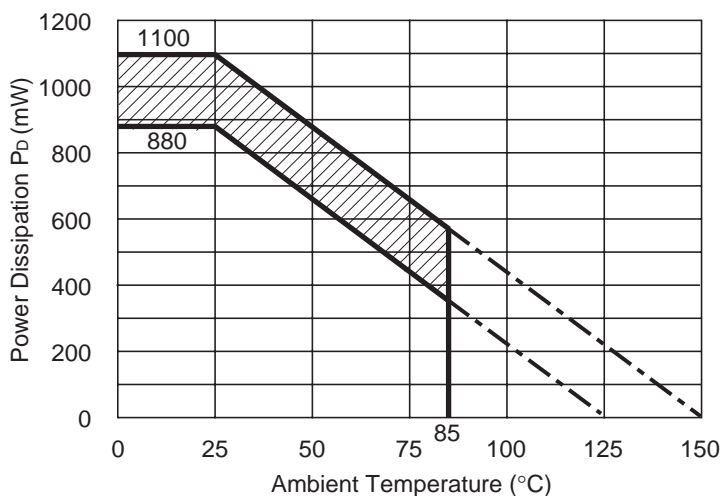
(Power Dissipation (DFN(PLP)2020-8) is substitution of DFN(PLP)1820-6.)

Measurement Conditions

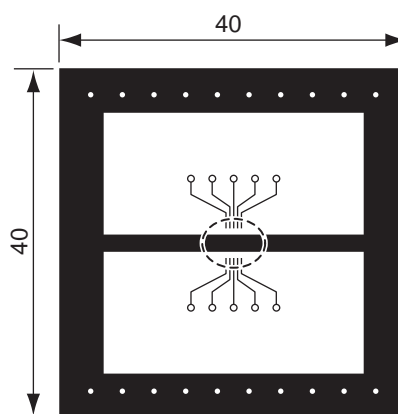
	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-holes	φ0.54mm × 30pcs

Measurement Results (T<sub>opt</sub>=25°C, T<sub>jmax</sub>=125°C)

	Standard Land Pattern
Power Dissipation	880mW
Thermal Resistance	$\theta_{ja}=(125-25^\circ\text{C})/0.88\text{W}=114^\circ\text{C/W}$
	$\theta_{jc}=22.8^\circ\text{C/W}$



**Power Dissipation**



**Measurement Board Pattern**

○ IC Mount Area (Unit: mm)

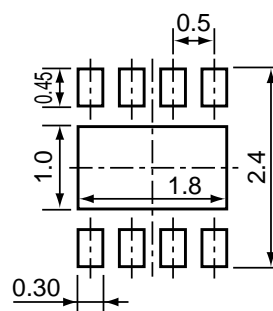
The above graph shows the Power Dissipation of the package based on T<sub>jmax</sub>=125°C and T<sub>jmax</sub>=150°C.

Operating the IC in the shaded area in the graph might have an influence it's lifetime.

Operating time must be within the time limit described in the table below, in case of operating in the shaded area.

Product Name	Operating time	Estimated years*
RP150K RP151K	13,000H	9 年

### RECOMMENDED LAND PATTERN



(Unit: mm)

\*The volume is calculated on the supposition that operating four hours/day.

